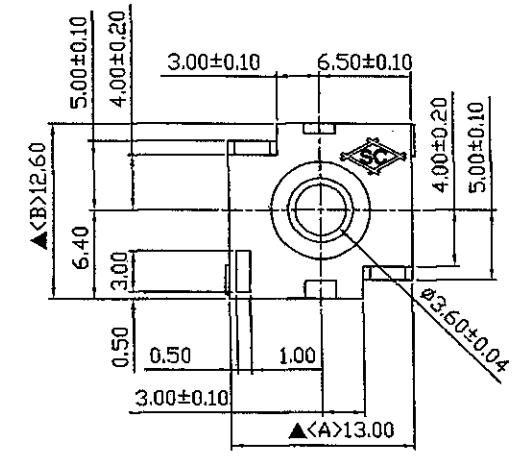
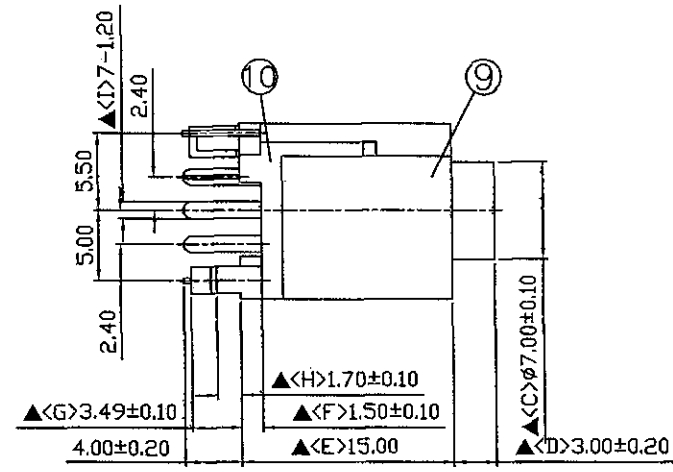
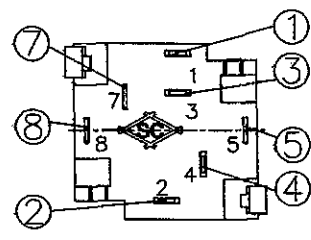


(1) Resistance to soldering heat test.
 The jack terminal shall be dipped in solder under the condition as specified below.

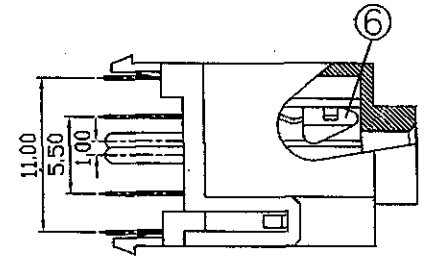
(a) The terminal for a printed circuit board :
 Temperature of solder : 225°C±5°C Dip time : 5±1 seconds

(b) The terminal for a lead wire : Temperature of solder : 350°C±10°C
 Dip time : 3±0.5 seconds

(2) Test Condition : (a) Solder time : 3±0.5sec
 (b) Solder pot : 230±5°C

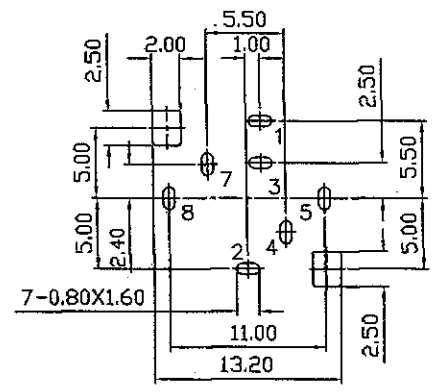


10.	Back Cover	PBT +15%G	1	Black Color
9.	Housing	PBT	1	Black Color
8.	Break Terminal	0.25T Phosphor Bronze	1	Silver Plated
7.	Separator Terminal	0.3T Brass	1	Silver Plated
6.	Insulator	POM	2	White Color
5.	Break Terminal	0.25T Phosphor Bronze	1	Silver Plated
4.	Separator Terminal	0.3T Brass	1	Silver Plated
3.	Ring Spring	0.25T Phosphor Bronze	1	Silver Plated
2.	Tip Spring	0.35T Phosphor Bronze	1	Silver Plated
1.	Earth Spring	0.25T Phosphor Bronze	1	Silver Plated
NO.	Description	Material	Q'TY	Finish



RoHS
Compliant

SPECIFICATIONS:
 Contact Resistance : 30mΩ max
 Insulation Resistance : 100MΩ min. at DC 500V
 Dielectric Withstanding Voltage: AC 500V for one minute
 Remark: ▲: The Most Important Dimension



Pin Hole Layout
(Jack Bottom View)

DATE	DWN	CHKD
01.06.2012		

PART NAME : 3.5φ PHONE JACK

TOLERANCE : ±0.3mm UNLESS OTHERWISE SPECIFIED

UNIT:mm

SHOGYO INTERNATIONAL CORP.

SCJ340P00(*)S0B00G